



IAB110P Integrated Telecom Circuits

Parameter	Rating	Units
Blocking Voltage	350	V _P
Load Current	100	mA
Max On-resistance	35	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Three Functions in One Package
- Bidirectional Current Sensing
- Bidirectional Current Switching
- FCC Compatible
- No EMI/RFI Generation
- Small 16-Pin SOIC Package (PCMCIA Compatible)
- · Machine Insertable, Wave Solderable
- Tape & Reel Versions Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringer Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
 - Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The IAB110P Multifunction Telecom switch combines one 350V single-pole, normally open (1-Form-A) relay; one 350V single-pole, normally closed (1-Form-B) relay; and one bidirectional optocoupler in a single package. The relays use Clare's patented, optically coupled OptoMOS® technology to provide 3750V_{rms} of input to output isolation, while the inputs control the relay outputs using highly efficient GaAIAs infrared LEDs.

The IAB110P allows telecom circuit designers to combine three discrete functions in a single component, whose small package uses less space than traditional discrete component solutions.

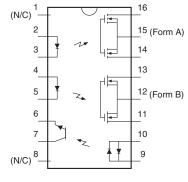
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1305490
- EN/IEC 60950-1 Certified Component: TUV Certificate: B 09 07 49410 006

Ordering Information

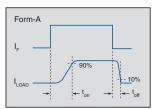
ĺ	Part #	Description	
	IAB110P	16-Pin SOIC (50/Tube)	
	IAB110PTR	16-Pin SOIC (1000/Reel)	

Pin Configuration

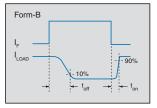


- 1. (N/C) 2. + LED - Form A Relay #1 3. – LED - Form A Relay #1
- 4. + LED Form B Relay #2
- LED Form B Relay #2
 Emitter Phototransistor
- Emitter Phototransistor
 Collector Phototransistor
 (N/C)
- 9. LED Phototransistor +/-
- 10. LED Phototransistor -/+
- 11. Output Form B Relay #2
- 12. Common Source Relay #2 13. Output - Form B Relay #2
- 13. Output Form B Relay #2
 14. Output Form A Relay #1
- 15. Common Source Relay #1
- 16. Output Form A Relay #1

Switching Characteristics of Normally Open Devices



Switching Characteristics of Normally Closed Devices











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units	
Input Control Current, Relay	50	mA	
Total Package Dissipation ¹	1	W	
Isolation Voltage, Input to Output	3750	V _{rms}	
Operational Temperature	-40 to +85	°C	
Storage Temperature	-40 to +125	°C	

¹ Derate linearly 1.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @25°C: Relay Section

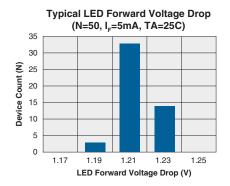
Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics	`					
Blocking Voltage (Peak)	$I_L=1\mu A$	V _L	-	-	350	V _P
Load Current						
Continuous	-	I _L	-	-	100	mA
Peak	t=10ms	I _{LPK}	-	-	350	mA
On-Resistance	I _L =100mA	R _{ON}	-	-	35	Ω
Off-State Leakage Current	V _L =350V, T _J =25°C	I _{LEAK}	-	-	1	μΑ
Switching Speeds						
Turn-On	-EmA \/ -10\/	t _{on}	-	-	3	ms
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	3	ms
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics				1		'
Input Control Current	I _L =100mA	I _F	-	-	5	mA
Input Dropout Current	I _L =1mA	I _F	0.4	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μА

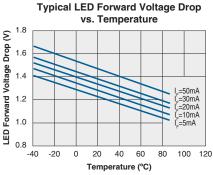
Electrical Characteristics @25°C: Detector Section

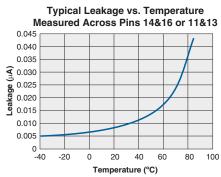
Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Phototransistor Blocking Voltage	I _C =10μA	BV _{CEO}	20	50	-	V
Phototransistor Dark Current	V _{CE} =5V, I _F =0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _C =2mA, I _F =16mA	V _{SAT}	-	0.3	0.5	V
Current Transfer Ratio	I _F =6mA, V _{CE} =0.5V	CTR	33	-	-	%
Input Characteristics						
Input Control Current	$I_{C}=2mA, V_{CE}=0.5V$	I _F	-	2	6	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Input Current (Detector Must be Off)	$I_C=1\mu A, V_{CE}=5V$	-	5	25	-	μА
Capacitance, Input to Output	V _L =50V, f=1MHz	C _{I/O}	-	3	-	pF
Isolation, Input to Output	-	V _{I/O}	3750	-	-	V _{rms}

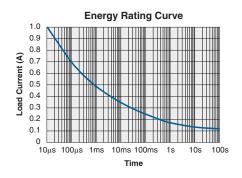


DEVICE PERFORMANCE DATA*

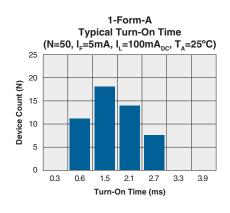


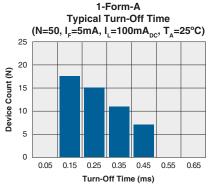


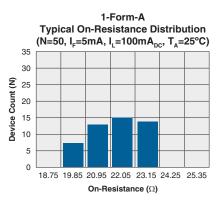


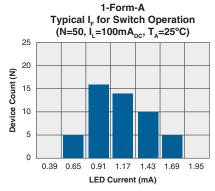


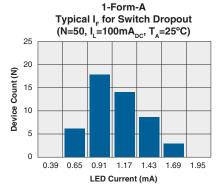
1-FORM-A RELAY PERFORMANCE DATA*

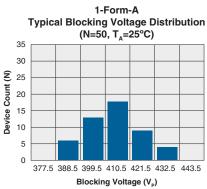








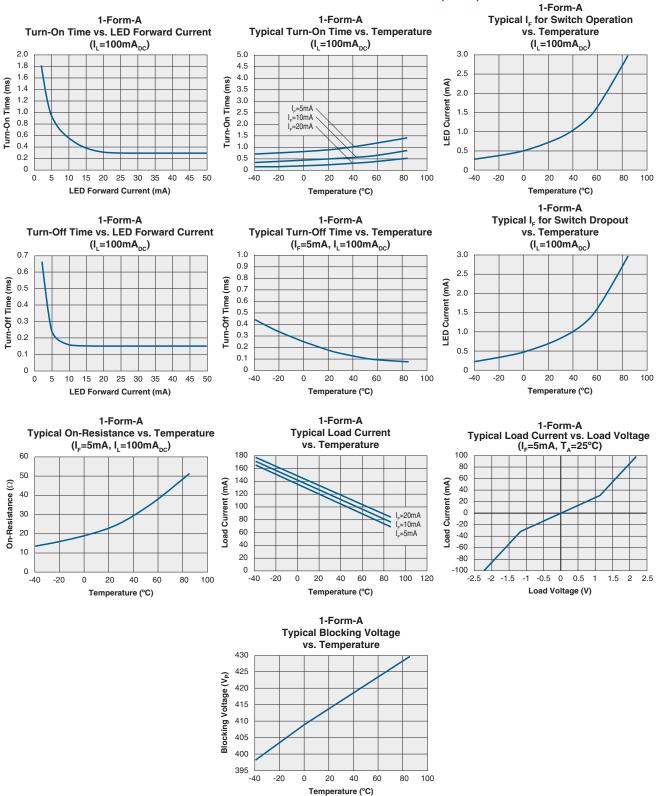




^{*} The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



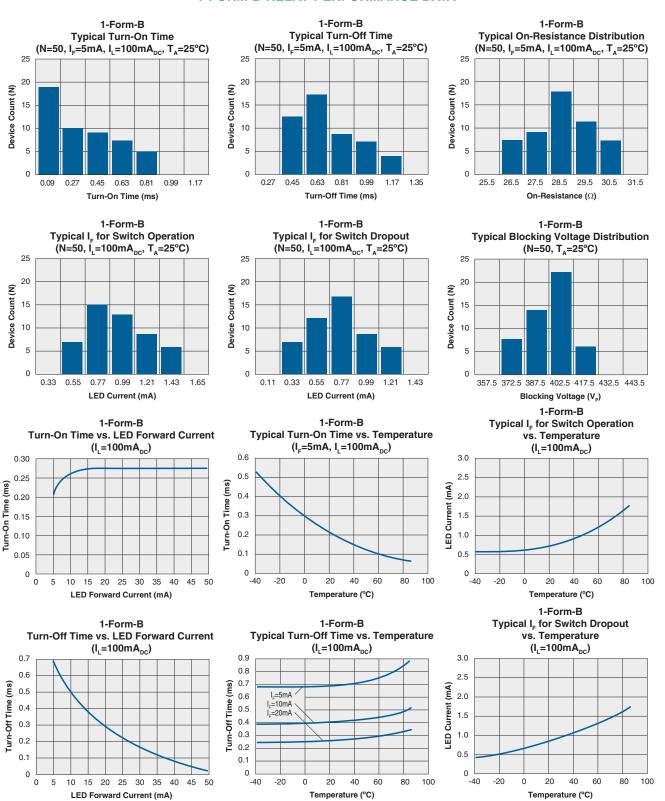
1-FORM-A RELAY PERFORMANCE DATA (cont.)*



^{*} The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



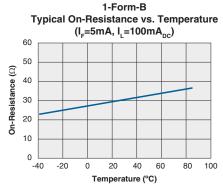
1-FORM-B RELAY PERFORMANCE DATA*

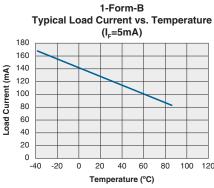


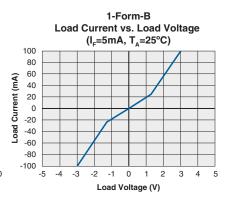
^{*} The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

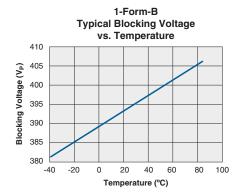


1-FORM-B RELAY PERFORMANCE DATA (cont.)*

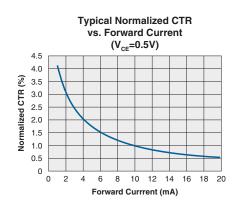


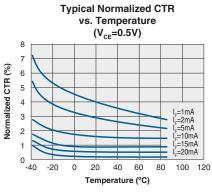


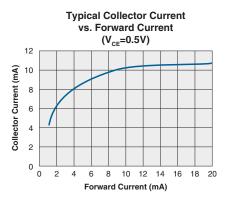




DETECTOR PERFORMANCE DATA*







^{*} The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingression. Clare classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to

the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating		
IAB110P	MSL 1		

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time		
IAB110P	260°C for 30 seconds		

Board Wash

Clare recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since Clare employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.









MECHANICAL DIMENSIONS

IAB110P 10.160±0.381 **PCB Land Pattern** (0.400±0.015) 0.254 ±0.0127 PIN 16 (0.010±0.0005) 10.363±0.127 (0.408±0.005) 9.30 0.635 X 45° 7.493±0.127 (0.366)(0.025 X 45°) 1.016 TYP (0.295±0.005) 1.90 (0.040 TYP) (0.075)PIN 1 1.270 TYP (0.050)(0.050 TYP) 2.108 MAX (0.083 MAX) 0.60 See Note 3 (0.024)**DIMENSIONS** mm (inches) 0.406 TYP NOTES: (0.016 TYP) 1. Coplanarity = 0.1016 (0.004) max. Lead to Package Standoff: 8.890 TYP 2. Leadframe thickness does not include solder plating MIN: 0.0254 (0.001) (0.350 TYP) (1000 microinch maximum). MAX: 0.102 (0.004)

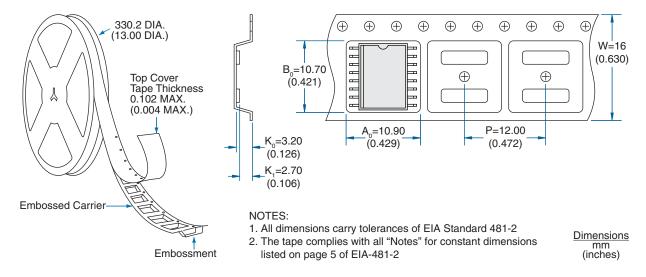
3. Sum of package height, standoff, and coplanarity

does not exceed 2.108 (0.083).

IAB110P Tape & Reel

0.508±0.1016

(0.020±0.004)



For additional information please visit our website at: www.clare.com

Clare, Inc. makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice. Neither circuit patent licenses nor indemnity are expressed or implied. Except as set forth in Clare's Standard Terms and Conditions of Sale, Clare, Inc. assumes no liability whatsoever, and disclaims any express or implied warranty, relating to its products including, but not limited to, the implied warranty of merchantability, fitness for a particular purpose, or infringement of any intellectual property right.

The products described in this document are not designed, intended, authorized or warranted for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or where malfunction of Clare's product may result in direct physical harm, injury, or death to a person or severe property or environmental damage. Clare, Inc. reserves the right to discontinue or make changes to its products at any time without notice.